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*2814*  
S/N 09/854,539

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Intel Corporation et al.

Serial No.: 09/854,539

Filed: May 14, 2001

Title: POLYMERIC ENCAPSULATION MATERIAL  
WITH FIBROUS FILLER FOR USE IN  
MICROELECTRONIC CIRCUIT PACKAGING

Customer Number: 21186



Examiner: Alonzo Chambliss

Group Art Unit: 2814

Docket No.: 884.415US1

**RESPONSE UNDER 37 CFR § 1.111**

MS Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

This responds to the Office Action mailed on February 8, 2006. Please consider the remarks as follows.